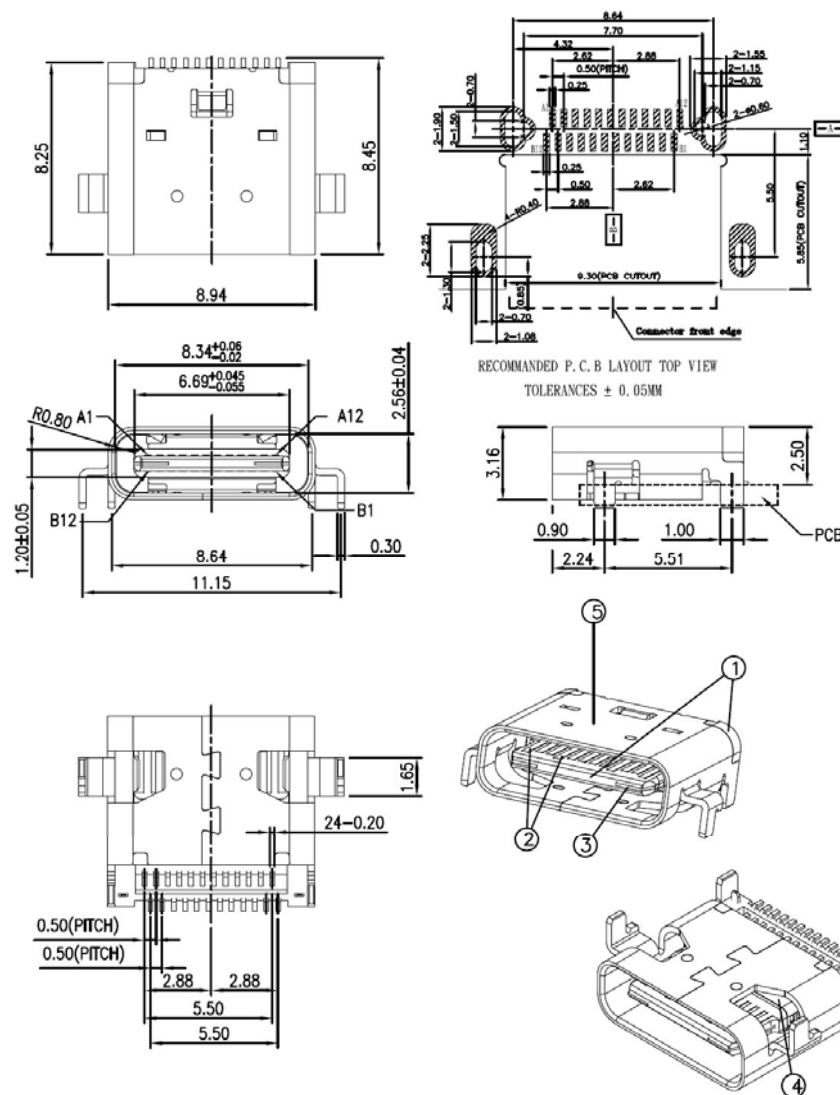




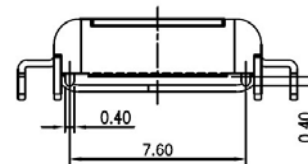
NOTES :

1. MATERIAL:

- 1.1 HOUSING : THERMOPLASTIC,HIGH TEMP,UL94V-0 .
- 1.2 CONTACT : COPPER ALLOY.
- 1.3 MID-PLATE : STAINLESS STEEL.
- 1.4 EMC PAD : COPPER ALLOY.
- 1.5 SHELL : STAINLESS STEEL.

2. FINISH:

- 2.1 CONTACT : Au PLATING ON CONTACT AREA
80u"(Min) NICKEL UNDERPLATING OVERALL .
- 2.2 SHELL / MID-PLATE : GOLD FLASH ON SOLDER AREA .
- 2.3 EMC PAD : NICKEL PLATING OVERALL .



PIN ASSIGNMENT											
A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	TX1-	TX1-	VBUS	CC1	D+	D-	SBU1	VBUS	RX2-	RX2+	GND
GND	RX1+	RX1-	VBUS	SBU2	D-	D+	CC2	VBUS	TX2-	TX2-	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1

ORDERING INFORMATION:

P/N UC31C-24FB_{xx}
1

1. CONTACT FINISH:

- "05" 5 MICROINCH GOLD
"15" 15 MICROINCH GOLD
"30" 30 MICROINCH GOLD

DIMENSIONS ARE IN MILLIMETERS		Ratioplast Electronics		RoHS COMPLIANT	
TOLERANCE UNLESS OTHERWISE SPECIFIED		PART NO.	UC31C-24FBxx	TITLE: USB3.1 C TYPE 24 PIN FEMALE CONNECTOR SMT TYPE	
LINEAR	0.0±0.25 0.00±0.15	DATE	July / 22 / 2015		
ANGLES	± 3	NOT SCALED DRAWING		DRAWING NO.	UC31C-24FBxx